



# December 2018

## Quarterly Reliability Report

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# Peregrine Semiconductor Reliability System

The Quarterly Reliability Report is a compilation of reliability stress test results that crosses the entire product & technology family of Peregrine Semiconductor Corporation products. Data is collected on a regular basis through the efforts of product and process qualifications, standard product monitoring and lot acceptance testing. To date, a total of **75,650 devices** have been tested in HTOL with a total of **6.73 billion equivalent device hours**. The overall failure rate for the pSemi family of products is **0.14 FIT**. (Using E<sub>aa</sub> = 0.7eV, T<sub>j</sub>=55°C at 60% UCL)

Peregrine Semiconductor reliability testing standards conform to industry standard qualification procedures as detailed in the JEDEC and/or Military Standard guidelines. In addition, where clear guidelines have not been established yet, Peregrine Semiconductor has developed stringent reliability requirements to ensure consistent high reliability performance.

Peregrine Semiconductor makes use of accelerated life testing results, along with thermal acceleration factors in the prediction of failure rates. High Temperature Operating Life (HTOL) stress testing is performed at accelerated voltage and temperature conditions which are based on MIL-STD-883 M1005.9 and Jedec JESD22 A108 standards. Resulting data collected from HTOL tests is de-rated to a typical use operating junction temperature (T<sub>j</sub>) of 55°C. Early Life Failure Rate (ELFR) is derived after 48-hr performance.

Peregrine Semiconductor conducts an ongoing product reliability monitoring program to evaluate sample products from high volume, major product families on a quarterly basis. The reliability monitoring process is a continuously improving system within Peregrine Semiconductor as we strive for superior product knowledge and performance.

Peregrine Semiconductor performs the majority of Reliability testing using an ISO17025 certified test laboratories located in Irvine, CA and San Jose, CA. Regular auditing of the laboratory is performed to ensure compliance to ISO standards.

# Failure Rate Calculation

## Acceleration Factor (AF)

For a given failure mechanism, acceleration factor (AF), is the ratio of the time it takes for a certain fraction of the population to fail, following application of one stress or use condition, to the corresponding time at a more severe stress or use condition.

The industry uses the thermal acceleration model formula based on Arrhenius equation noted below:

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$$AF(T_{use}, T_{stress}) := e^{\frac{E_{aa}}{k_B} \cdot \left( \frac{1}{T_{use}} - \frac{1}{T_{stress}} \right)}$$

where:

$E_{aa} := 0.7 \text{ eV}$ , is the Apparent Activation Energy

$e = 2.718$ , is the base of natural logarithm

$k_B := 8.62 \cdot 10^{-5} \frac{\text{eV}}{\text{K}}$ , is the Boltzmann constant

$T_{use}$  &  $T_{stress}$ , are the use and stress test temperatures, respectively, in Kelvin

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## Sample Calculation

Find the Acceleration Factor (AF) with the following conditions.

(a)  $T_{use} := 55 \text{ }^\circ\text{C}$  and  $T_{stress} := 125 \text{ }^\circ\text{C}$

$$AF(T_{use}, T_{stress}) = 77.5$$

(b)  $T_{use} := 55 \text{ }^\circ\text{C}$  and  $T_{stress} := 150 \text{ }^\circ\text{C}$

$$AF(T_{use}, T_{stress}) = 258.7$$

# Failure Rate Calculation (continued)

## Failure in Time Calculation

Mean time to failure (M.T.T.F.) is defined as the average time it takes for a failure to occur. Failure in Time (F.I.T.) is the number of units predicted to fail in a billion ( $1e^9$ ) device hours at a specified temperature. After the life test is completed and accelerated device hour data is calculated, the failure rate is estimated using the Chi-Square approximation ( $\chi^2$ ) as follows:

$$FIT = \left( \frac{\chi^{2(2r+2)}}{2 * EDH} \right) * 1e^9$$

where:

$\chi^2 = chi$  square function  
 $r =$  number of failures  
 $EDH =$  equivalent device hours (units tested x test hours x AF)

## Sample Calculation

Given:            Units Tested (Sample Size) = 231 devices  
                     Test temperature = 150°C  
                     Test duration = 500 hours  
                     Failures = 0

EDH = (231 x 500 x 259.2) = 2.99E+7 equivalent device hours

$\chi^2$  @ 60% confidence level and 0 failures = 1.83

FIT (60% confidence level) = [1.83 / (2 x 2.99E+7)] x 1.0E+9 = 30.6 FIT



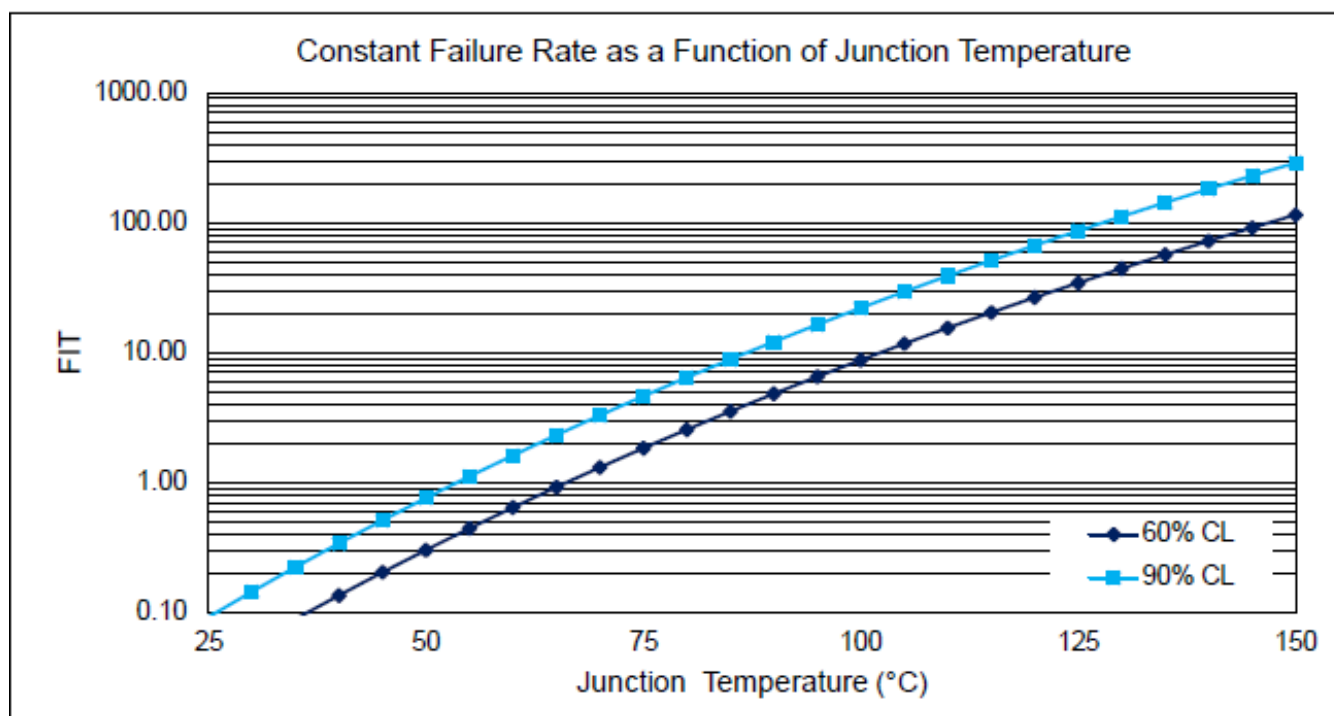
# Reliability Results

(FITs)

# UltraCMOS<sup>®</sup> 2 Process Technology

Generation : 500 nm CMOS Silicon Epi Process (U500E)  
 Units Tested : 28,090  
 Product Family : ASW, HPSW, DSA, DC-DC, MXR, PLL, PSR

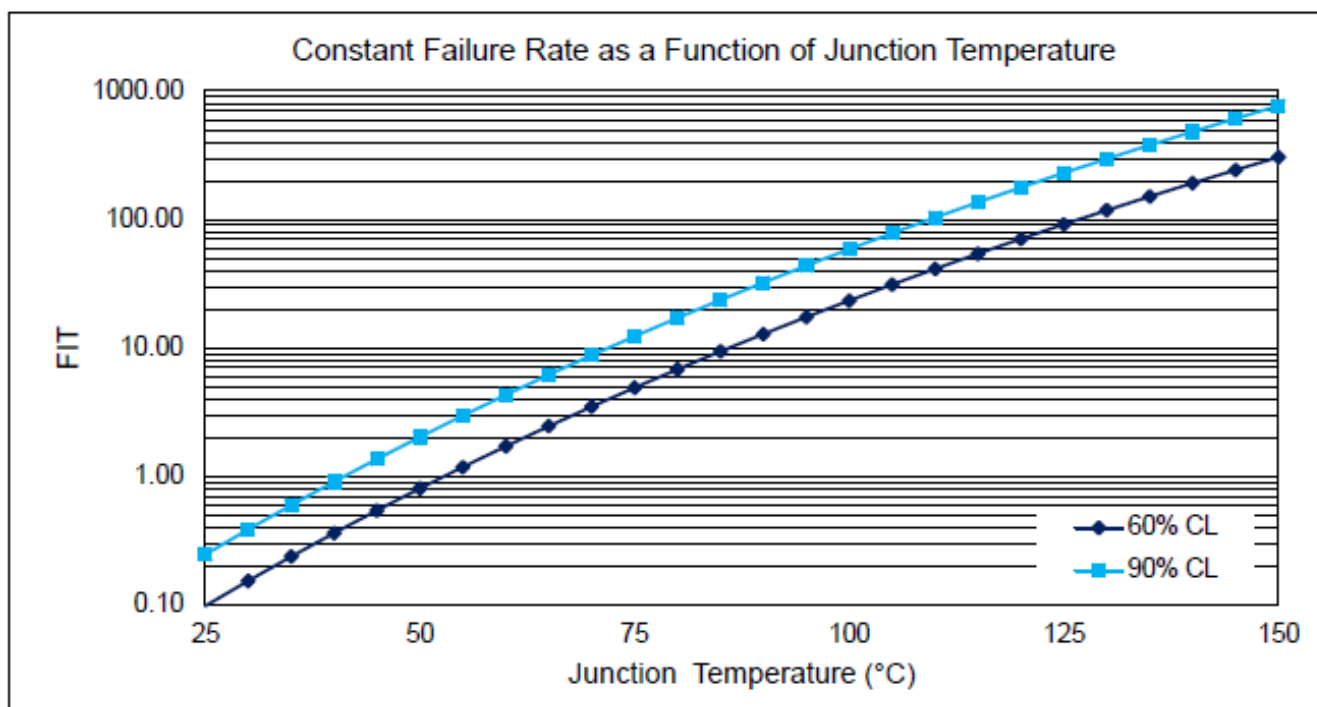
Standard Failure Rate Calculations at 55°C and 60% CL			
	EDH (hours)	FITs	MTTF (hours)
Early Life	2.45E+08	3.7	2.67E+08
Constant (Random)	2.07E+09	0.4	2.26E+09



# UltraCMOS<sup>®</sup> 3.5 Process Technology

Generation : 350 nm CMOS Silicon Epi Process (U350E)  
 Units Tested : 8,490  
 Product Family : ASW, HPSW, DTC, DSA, PSR

Standard Failure Rate Calculations at 55°C and 60% CL			
	EDH (hours)	FITs	MTTF (hours)
Early Life	1.03E+08	8.9	1.13E+08
Constant (Random)	7.77E+08	1.2	8.48E+08

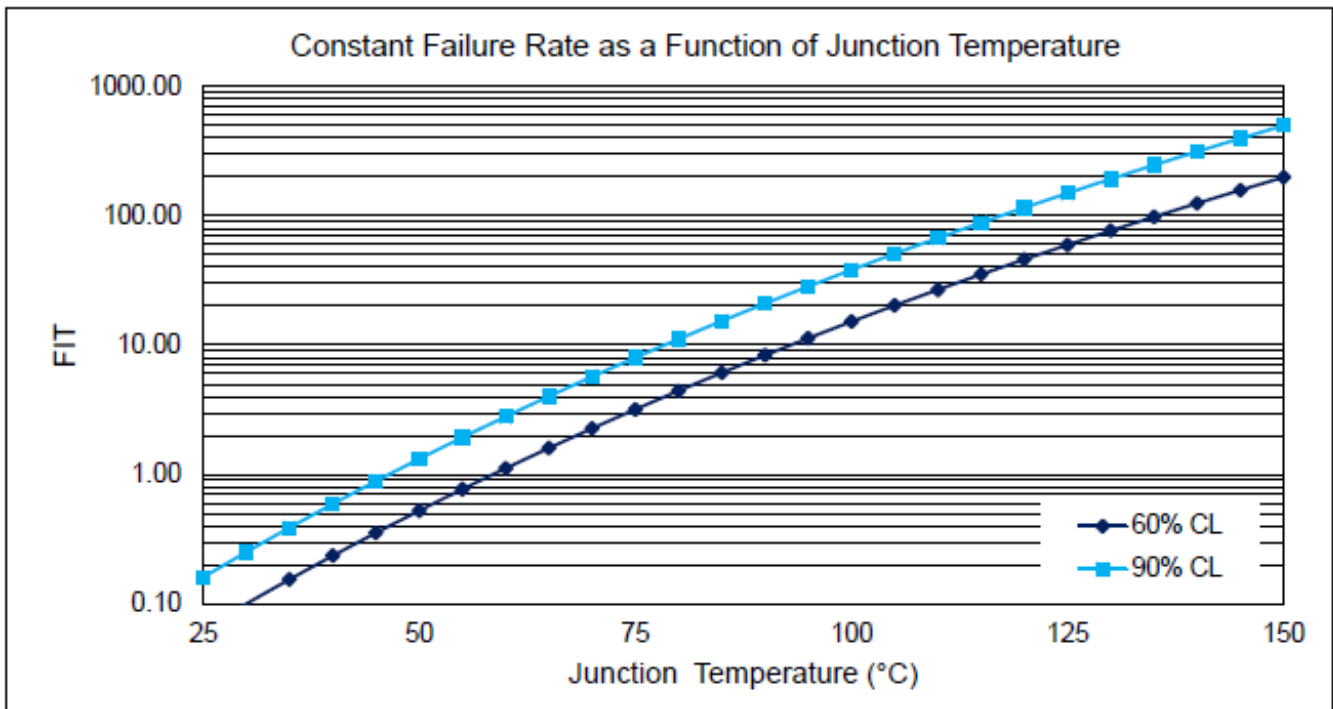




# UltraCMOS<sup>®</sup> 5 Process Technology

Generation : 350 nm CMOS Bonded Silicon Process (U350B)  
 Units Tested : 9,253  
 Product Family : ASW, DSA, DTC, HPSW, LMTR, MPAC, PLL, PSH

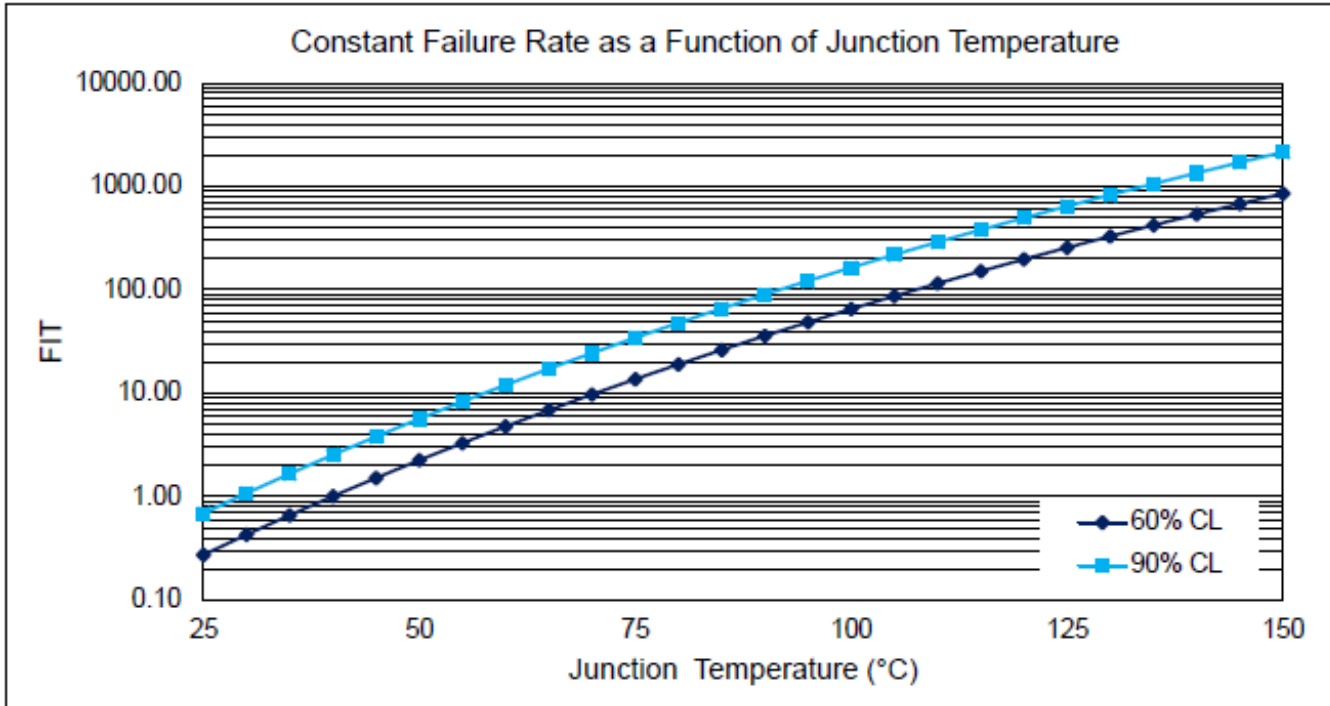
Standard Failure Rate Calculations at 55°C and 60% CL			
	EDH (hours)	FITs	MTTF (hours)
Early Life	1.14E+08	8.1	1.24E+08
Constant (Random)	1.19E+09	0.8	1.30E+09



# UltraCMOS<sup>®</sup> 6 Process Technology

Generation : 250 nm CMOS Silicon Epi Process (U250E2)  
 Units Tested : 2,198  
 Product Family : ASW, HPSW, PSR

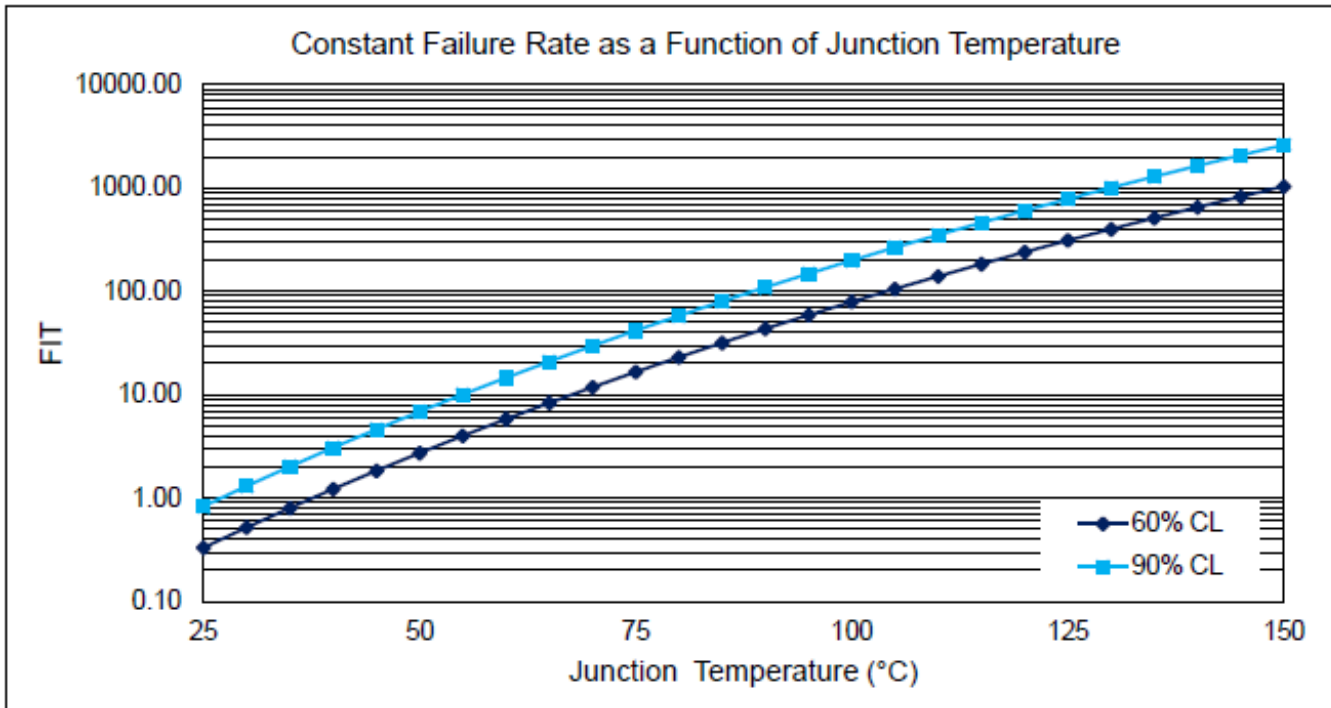
	Standard Failure Rate Calculations at 55°C and 60% CL		
	EDH (hours)	FITs	MTTF (hours)
Early Life Failure Rate	2.70E+07	33.9	2.95E+07
Constant (Random) Failure Rate	2.78E+08	3.3	3.03E+08



# UltraCMOS<sup>®</sup> 6.5 Process Technology

Generation : 250 nm CMOS Silicon Epi Process (U250E4)  
 Units Tested : 1,831  
 Product Family : ASW, DSA, HPSW

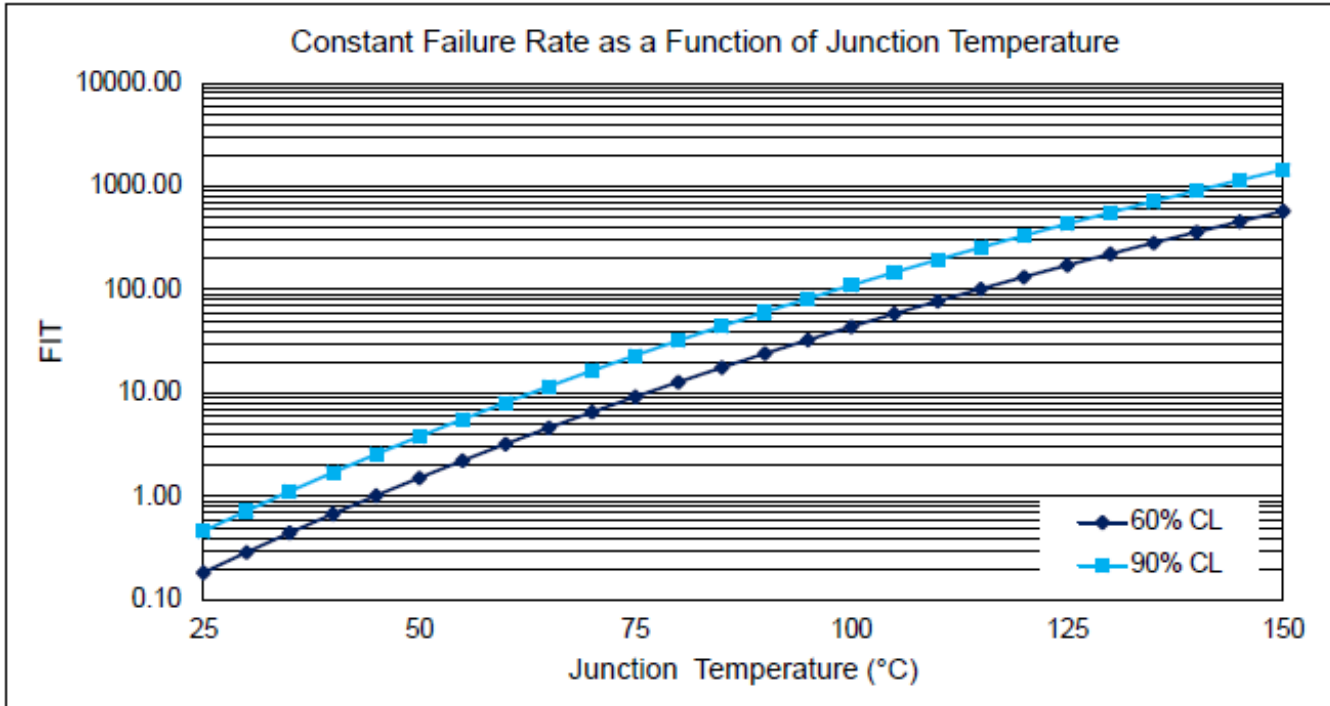
Standard Failure Rate Calculations at 55°C and 60% CL			
	EDH (hours)	FITs	MTTF (hours)
Early Life	1.83E+07	49.9	2.00E+07
Constant (Random)	2.29E+08	4.0	2.50E+08



# UltraCMOS<sup>®</sup> 8 Process Technology

Generation : 250 nm CMOS Bonded Silicon Process (U250B)  
 Units Tested : 3,215  
 Product Family : ASW, DSA, DTC, HPSW, LMTR, MPAC, MXR, PSR, DRV

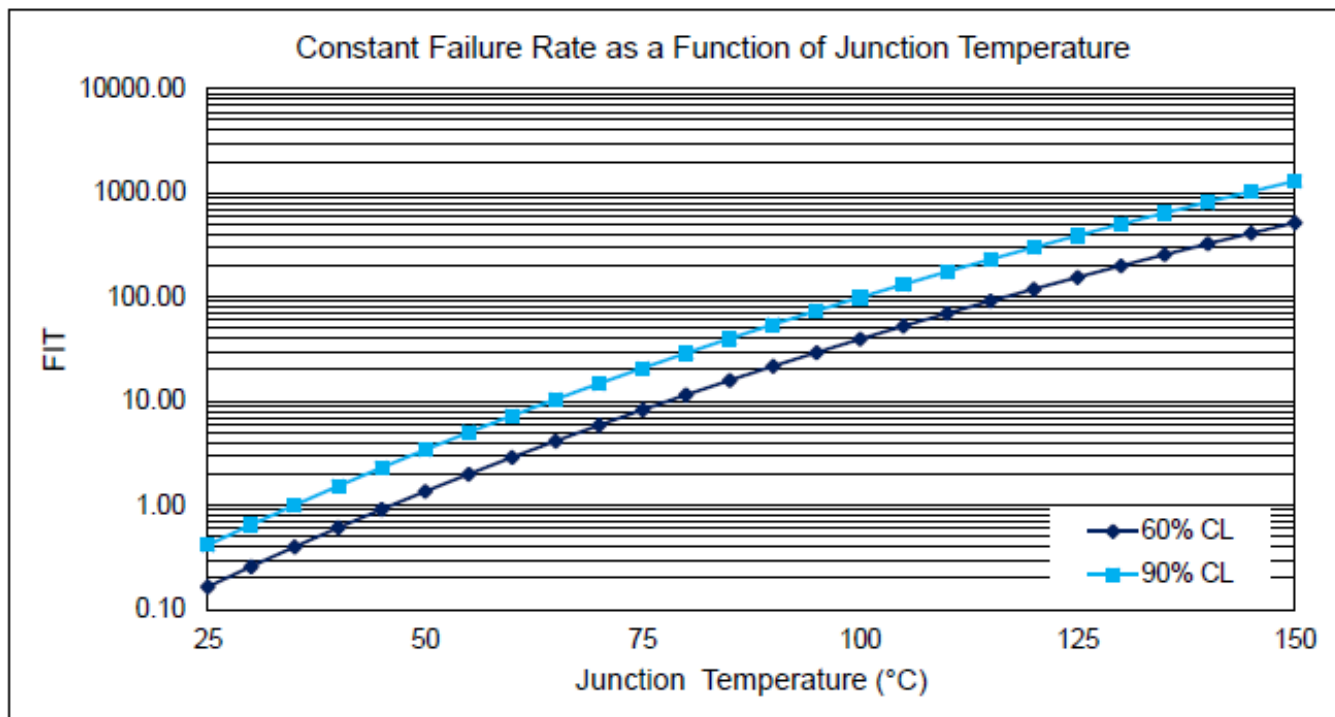
	Standard Failure Rate Calculations at 55°C and 60% CL		
	EDH (hours)	FITs	MTTF (hours)
Early Life Failure Rate	3.80E+07	24.1	4.15E+07
Constant (Random) Failure Rate	4.12E+08	2.2	4.50E+08



# UltraCMOS<sup>®</sup> 10 Process Technology

Generation : 130nm CMOS Silicon-On-Insulator in 200mm wafer(U130S1)  
 Units Tested : 3,806  
 Product Family : ASW

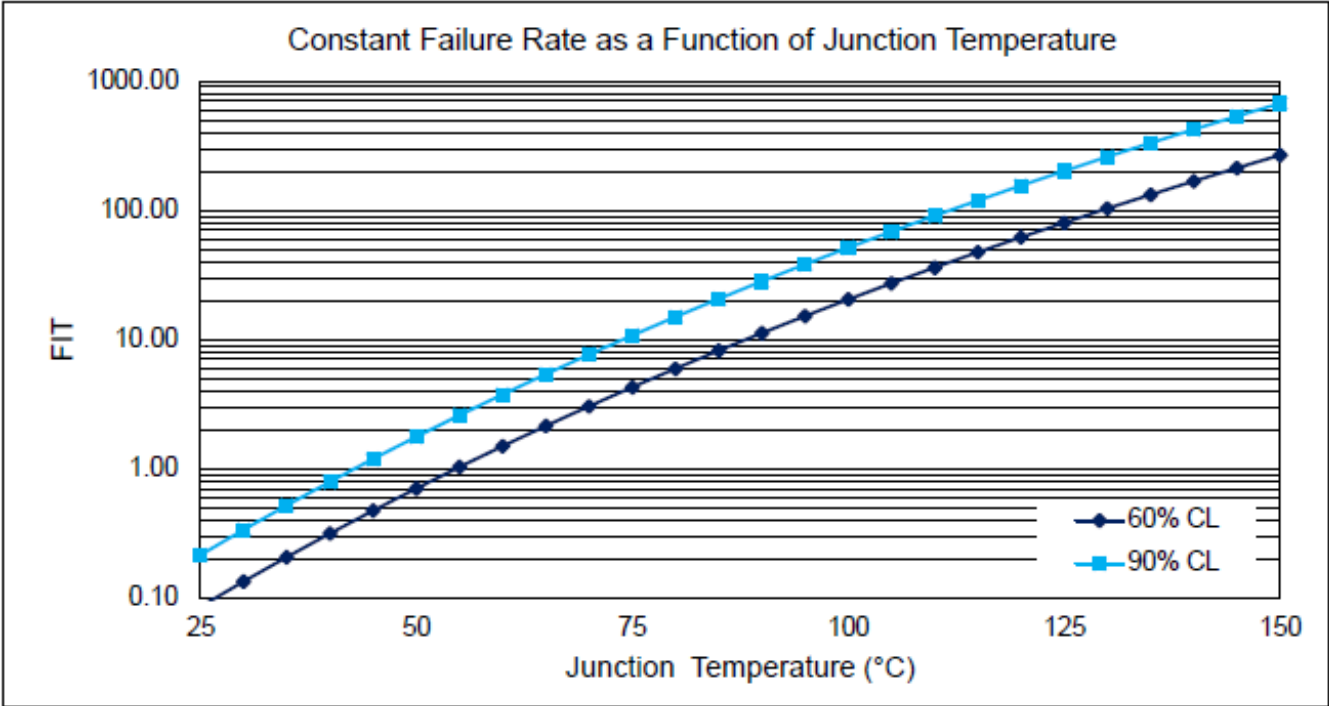
Standard Failure Rate Calculations at 55°C and 60% CL			
	EDH (hours)	FITs	MTTF (hours)
Early Life	4.06E+07	22.5	4.44E+07
Constant (Random)	4.59E+08	2.0	5.01E+08



# UltraCMOS<sup>®</sup> 11 Process Technology

Generation : 130nm CMOS Silicon-On-Insulator in 300mm wafer (U130S2)  
 Units Tested : 12,165  
 Product Family : ASW, HPSW, Amplifier (LNA, PA), DC-DC

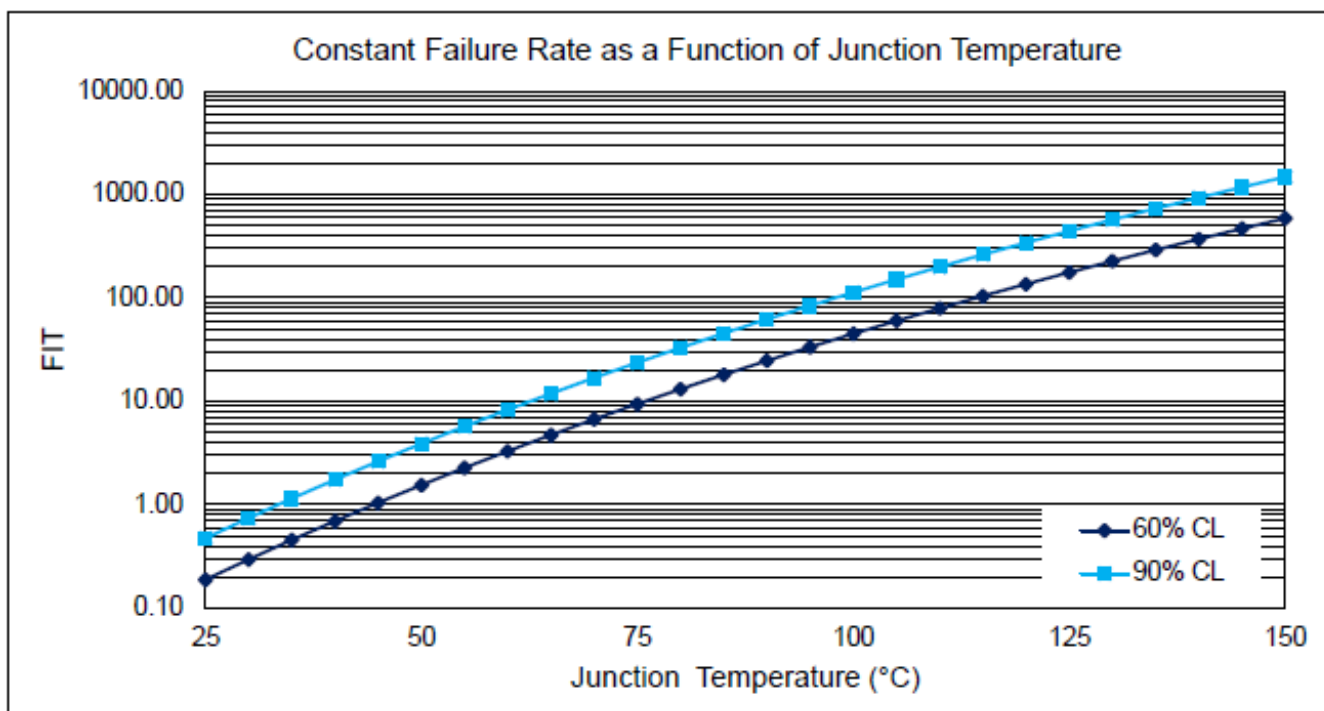
Standard Failure Rate Calculations at 55°C and 60% CL			
	EDH (hours)	FITs	MTTF (hours)
Early Life	7.09E+07	12.9	7.74E+07
Constant (Random)	8.88E+08	1.0	9.69E+08



# UltraCMOS<sup>®</sup> 12 Process Technology

Generation : 65nm CMOS Silicon-On-Insulator in 300mm wafer (U130S3)  
 Units Tested : 6,420  
 Product Family : ASW, PAC

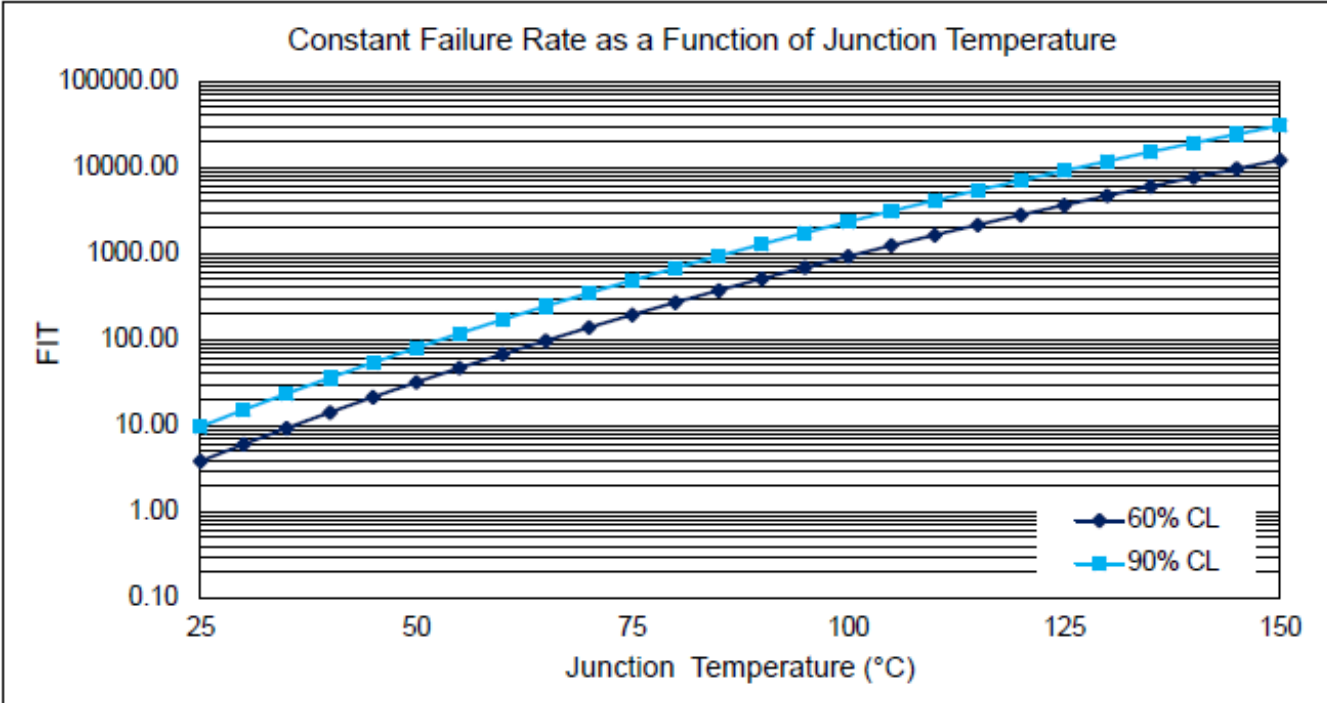
	Standard Failure Rate Calculations at 55°C and 60% CL		
	EDH (hours)	FITs	MTTF (hours)
Early Life Failure	4.50E+07	20.4	4.91E+07
Constant (Random)	4.04E+08	2.3	4.41E+08



# BCD GEN II Process Technology

Generation : TSMC 180 nm BCD Gen 2 process  
 Units Tested : 253  
 Product Family : Boost Converter

Standard Failure Rate Calculations at 55°C and 60% CL			
	EDH (hours)	FITs	MTTF (hours)
Early Life	9.42E+05	973.1	1.03E+06
Constant (Random)	1.96E+07	46.7	2.14E+07





# Amplifiers (LNA & PA)

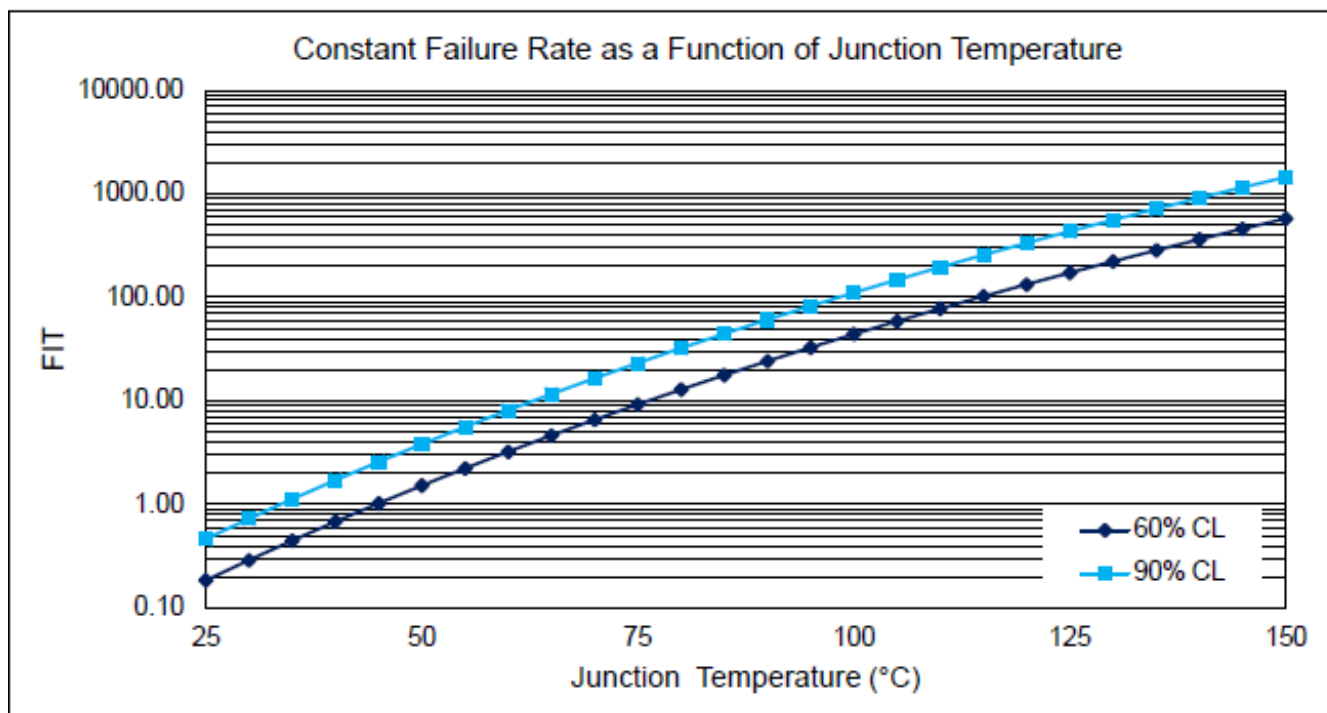
Description : UltraCMOS Low-Noise Amplifiers (LNA) and Power Amplifiers (PA)

Products in Family : PE471110/1, PE477181, PE478011, PE478021, PE478031, PE478070, PE479050, PE479070, PE521221, PE53210

Process Technology : UltraCMOS®11

Units Tested : 7,884

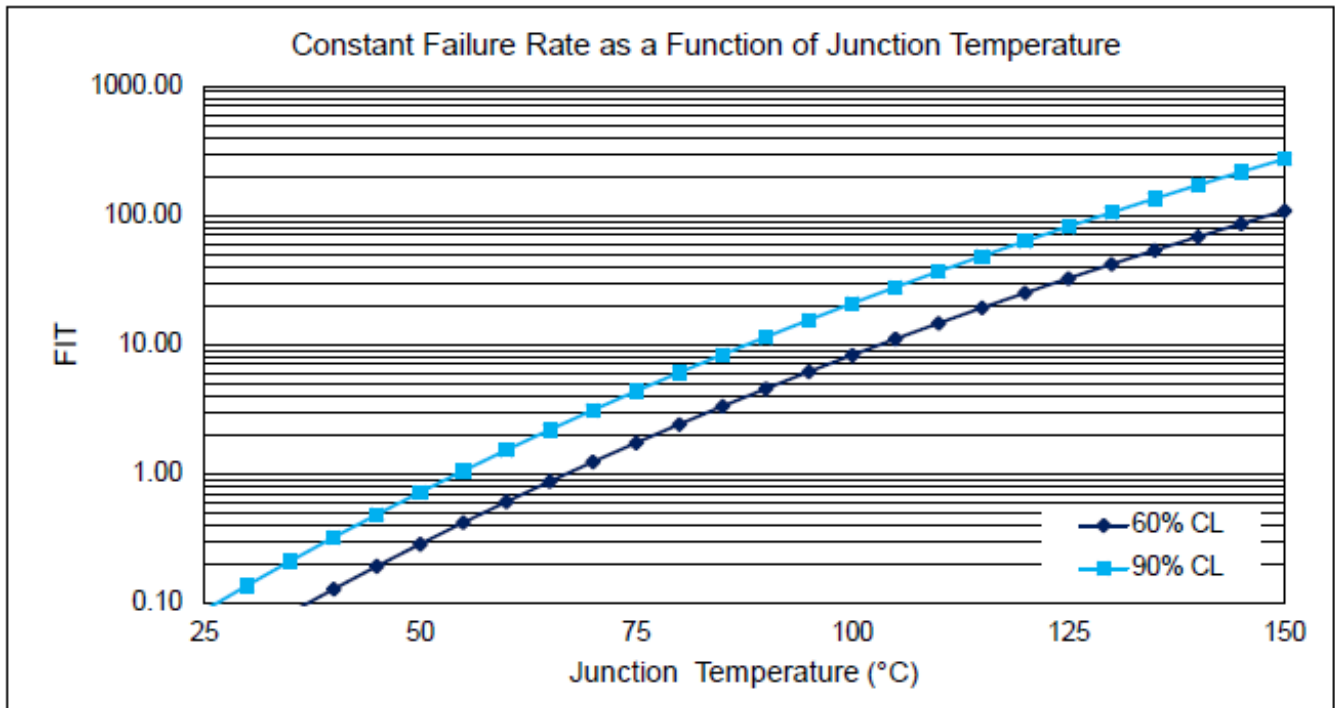
Standard Failure Rate Calculations at 55°C and 60% CL			
	EDH (hours)	FITs	MTTF (hours)
Early Life	3.30E+07	27.8	3.60E+07
Constant (Random)	4.11E+08	2.2	4.49E+08



# Antenna Switches (ASW)

- Description : Multi-pole & multi-throw high power handling antenna switch products for Mobile Wireless RF and Test Equipment /ATE applications.
- Products in Family : PE42108x, PE421120, PE42112x, PE42114x, PE42116x, PE421230, PE421240, PE42128x, PE42129x, PE421321, PE42145x, PE421510, PE421550, PE42159x, PE421603, PE42162x, PE421690, PE42170x, PE42171x, PE421729, PE421779, PE42181x, PE42188x, PE421890x, PE42194x, PE42195x, PE42197x, PE422020, PE423641, PE4255x, PE4257, PE42614x, PE42615x, PE42616x, PE42617x, PE4261x, PE4263x, PE42641, PE4266x, PE4267x, PE426810, PE42682x, PE42684x, PE42685x, PE42688x, PE4268x, PE426960, PE429002, PE42695x, PE426960/1, PE426970/1, PE4269x, PE426x, PE429561, PE613010, PE636030, PE636040, PE4211x
- Process Technology : UltraCMOS<sup>®</sup> 2, UltraCMOS<sup>®</sup> 3.5, UltraCMOS<sup>®</sup> 5, UltraCMOS<sup>®</sup> 6, UltraCMOS<sup>®</sup> 6.5, UltraCMOS<sup>®</sup> 8, UltraCMOS<sup>®</sup>10, UltraCMOS<sup>®</sup>11, UltraCMOS<sup>®</sup>12
- Units Tested : 23,045

		Standard Failure Rate Calculations at 55°C and 60% CL		
		EDH (hours)	FITs	MTTF (hours)
Early Life		2.55E+08	3.6	2.78E+08
Constant (Random)		2.19E+09	0.4	2.39E+09

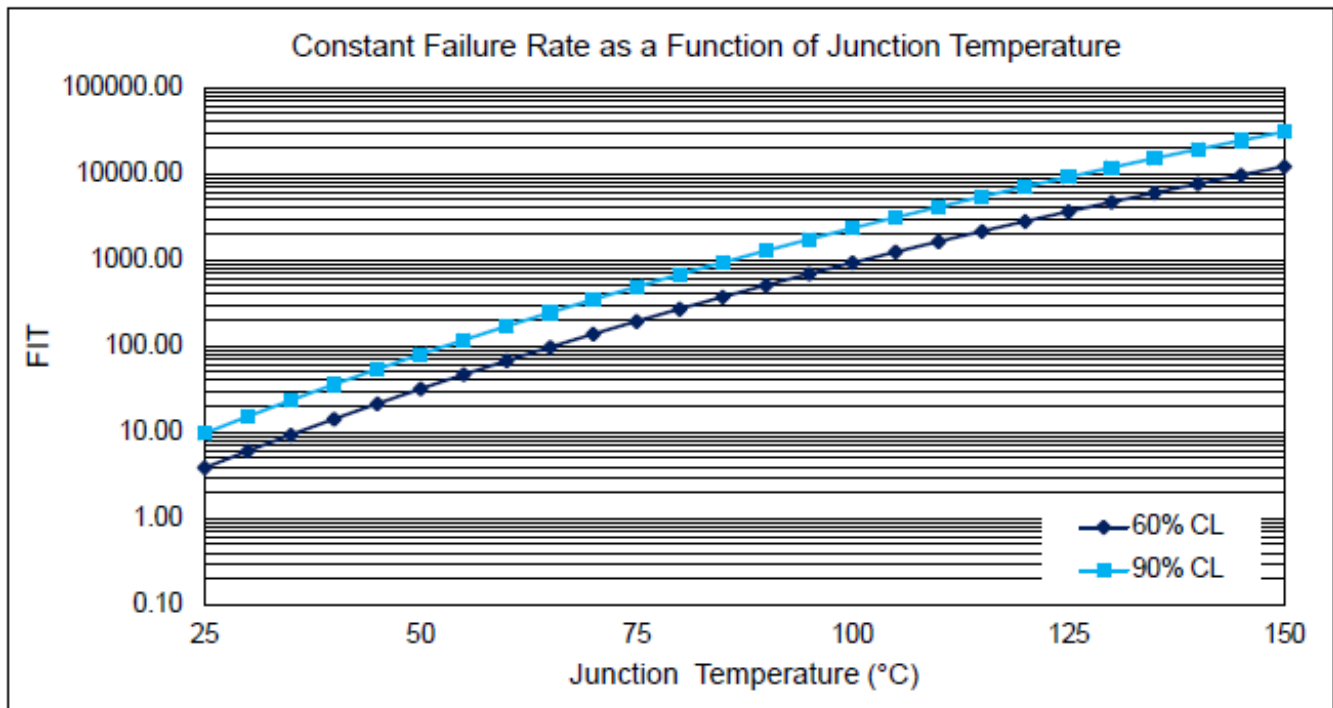


# Boost Converters

Description : These devices are ultra-high efficiency DC/DC converter solution with integrated programmable current sinks that drive strings of LEDs.

Products in Family : PE23363  
 Process Technology : BCD GEN II  
 Units Tested : 253

Standard Failure Rate Calculations at 55°C and 60% CL			
	EDH (hours)	FTs	MTTF (hours)
Early Life	9.42E+05	973.1	1.03E+06
Constant (Random)	1.96E+07	46.7	2.14E+07



# DC-DC Buck Regulators/Converters (DCDC)

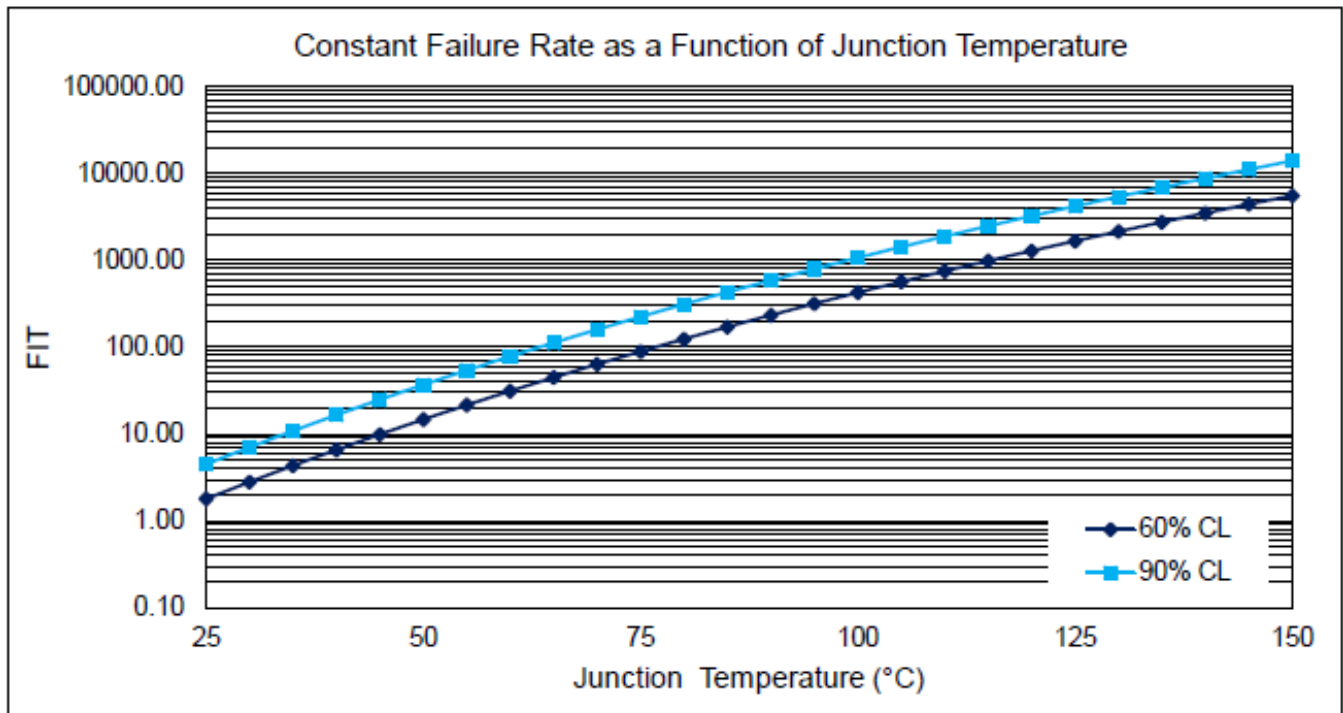
Description : These devices are radiation-hardened point-of-load (POL) buck regulators with integrated switches suited for DC-DC converter applications. This monolithic technology replaces multi-chip modules by offering superior performance, smaller size and reduced weight in sensitive space applications.

Products in Family : PE9915x, PE22100

Process Technology : UltraCMOS<sup>®</sup> 2, UltraCMOS<sup>®</sup> 11

Units Tested : 769

		Standard Failure Rate Calculations at 55°C and 60% CL		
		EDH (hours)	FITs	MTTF (hours)
Early Life		3.07E+06	298.4	3.35E+06
Constant (Random)		4.26E+07	21.5	4.65E+07



# Digital Step Attenuators (DSA)

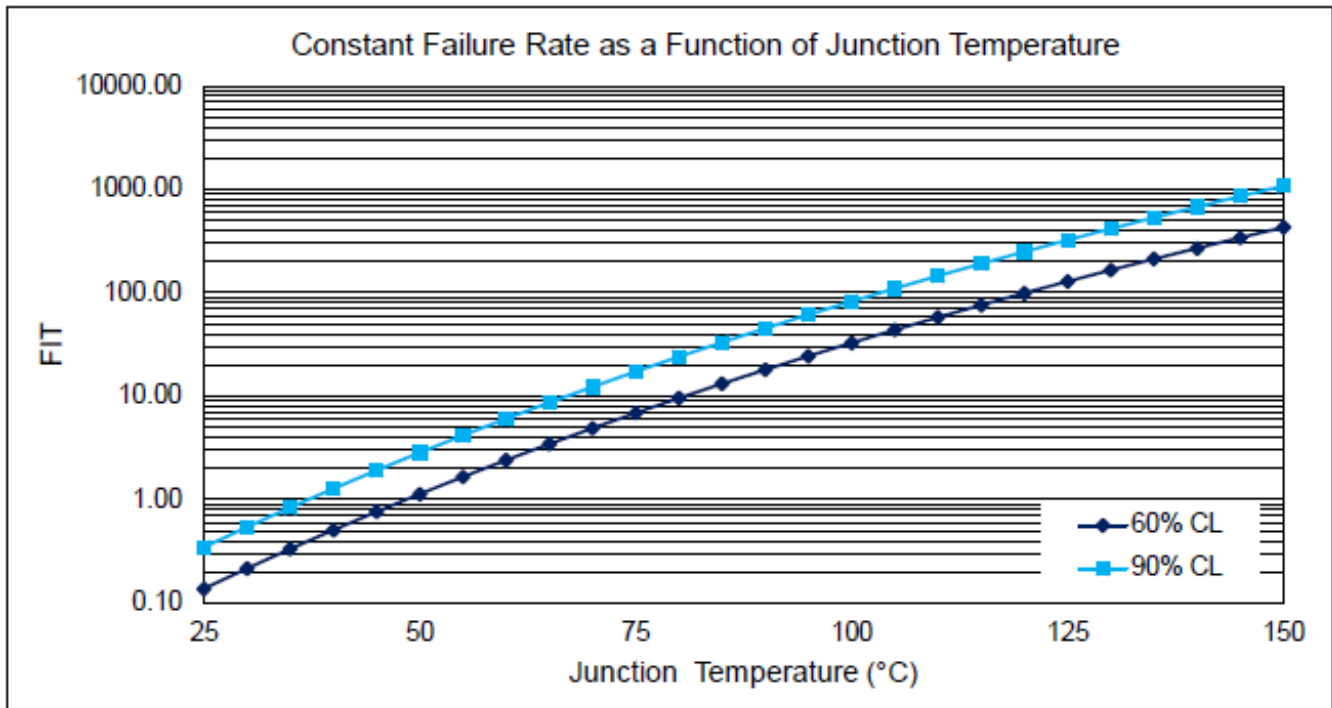
Description : 50Ω and 75Ω Digital Step Attenuators for wireless infrastructure, microwave, test equipment and high reliability space applications.

Products in Family : PE430x, PE4320x, PE43404, PE4350x, PE4360x, PE4370x, PE4371x, PE94302, PE431x, 94302-1x

Process Technology : UltraCMOS® 2, UltraCMOS® 3.5, UltraCMOS® 5, UltraCMOS® 8

Units Tested : 4,766

Standard Failure Rate Calculations at 55°C and 60% CL			
	EDH (hours)	FITs	MTTF (hours)
Early Life	4.96E+07	18.5	5.41E+07
Constant (Random)	5.52E+08	1.7	6.03E+08



# Digitally Tunable Capacitors (DTC)

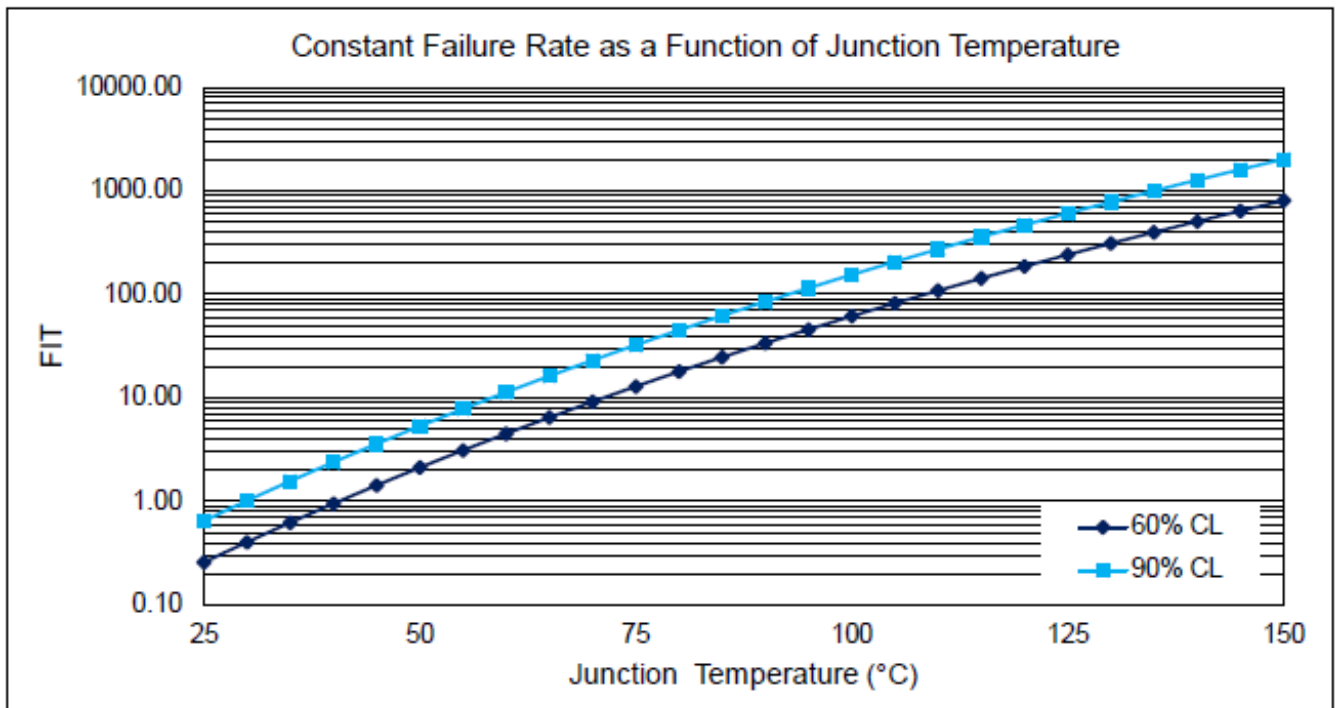
Description : Supports a wide range of tuning applications, from tuning the center frequency of mobile-TV and antennas, to tunable impedance matching and filters.

Products in Family : PE6230x, PE621010, PE621020, PE623060, PE623090, PE6490x, PE6410x, PE613040

Process Technology : UltraCMOS<sup>®</sup> 3.5, UltraCMOS<sup>®</sup> 5, UltraCMOS<sup>®</sup> 8

Units Tested : 2,379

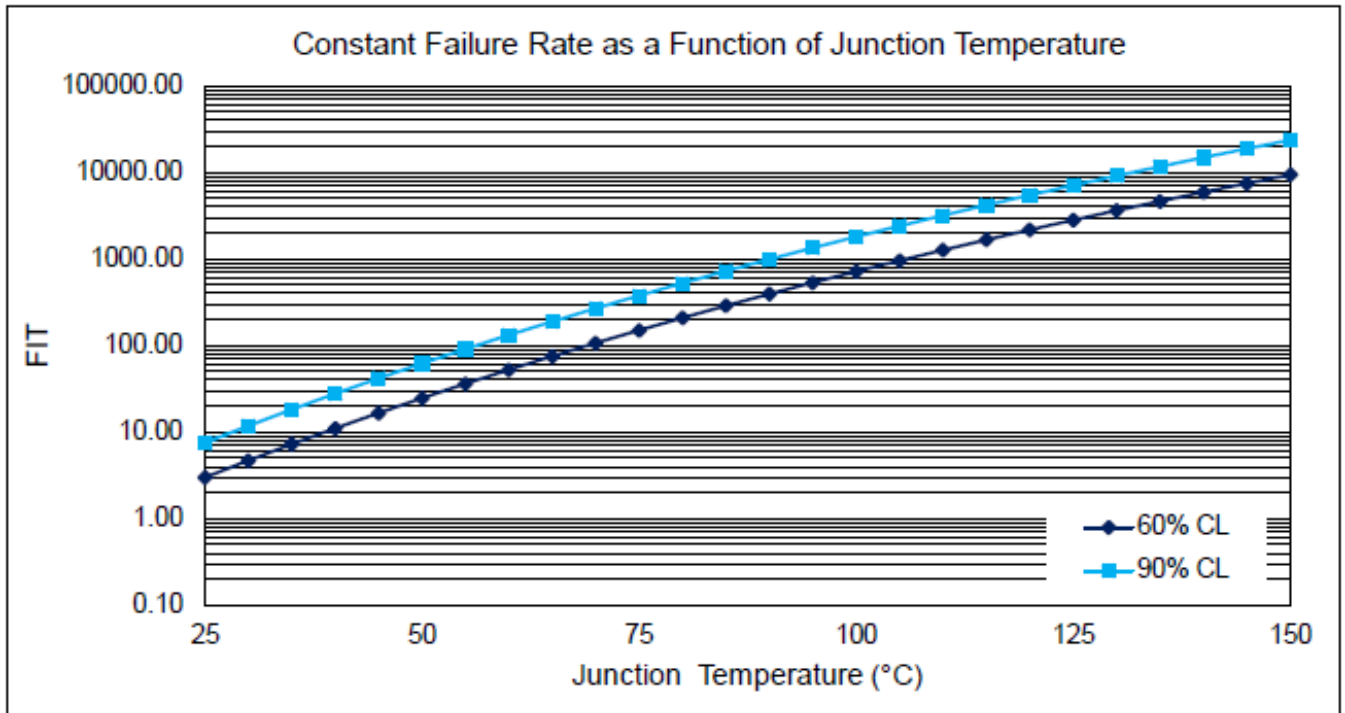
Standard Failure Rate Calculations at 55°C and 60% CL			
	EDH (hours)	FITs	MTTF (hours)
Early Life	2.82E+07	32.5	3.07E+07
Constant (Random)	2.95E+08	3.1	3.22E+08



# GaN Driver Product Family

Description : High-speed FET Driver  
 Products in Family : PE29100  
 Process Technology : UltraCMOS® 8  
 Units Tested : 327

Standard Failure Rate Calculations at 55°C and 60% CL			
	EDH (hours)	FITs	MTTF (hours)
Early Life	1.22E+06	752.9	1.33E+06
Constant (Random)	2.54E+07	36.1	2.77E+07



# High Performance Switches (HPSW)

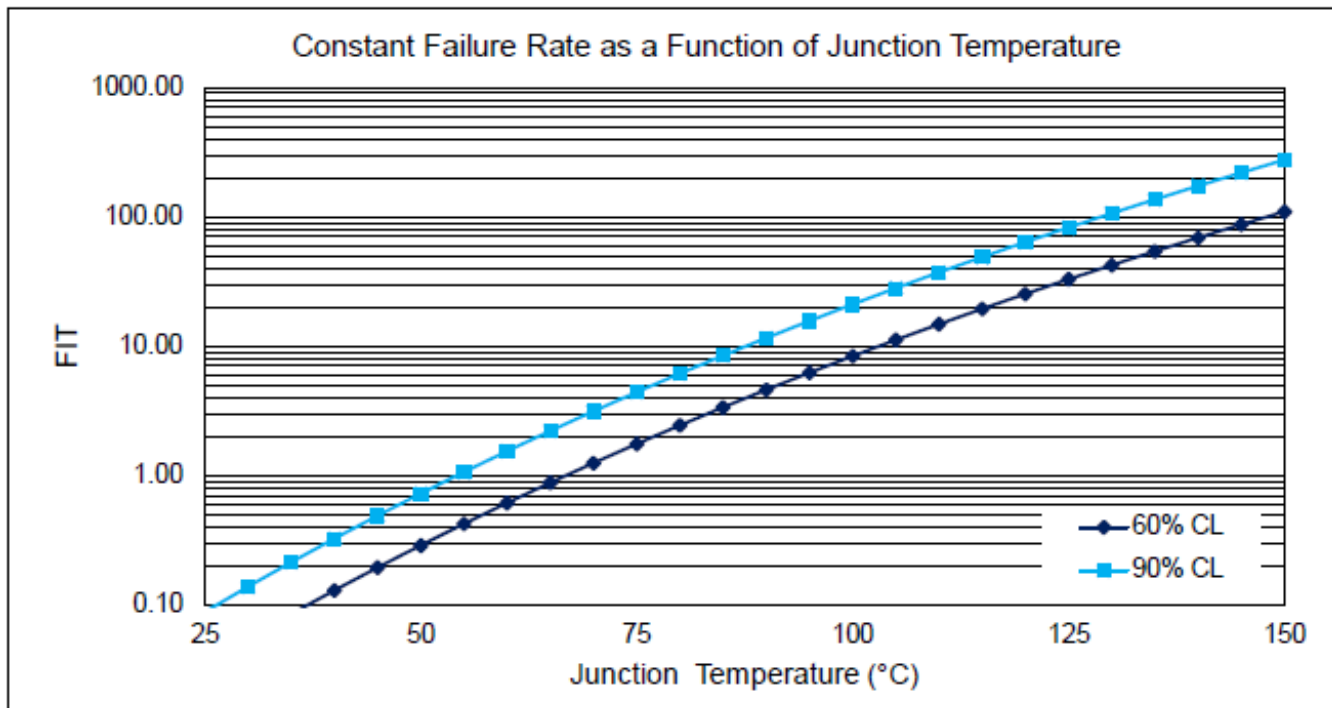
Description : High performance switch products for wireless RF, broadband and high reliability space switch applications.

Products in Family : PE42020, PE4210, PE4220, PE423422, PE42359, PE423x, PE423422, PE42412, PE4242x, PE4244x, PE4245x, PE424x, PE42512, PE4252x, PE4252x, PE4254x, PE4255x, PE42582, PE426525, PE426842, PE4272x, PE42742, PE42750, PE427x, PE42820, PE42823, PE42850, PE428x, PE43713, PE43711, PE84140, PE84244, PE9354, PE94257, PE9542x, PE33241, PE425x

Process Technology : UltraCMOS<sup>®</sup> 2, UltraCMOS<sup>®</sup> 3.5, UltraCMOS<sup>®</sup> 5, UltraCMOS<sup>®</sup> 8 UltraCMOS<sup>®</sup> 11

Units Tested : 21,544

Standard Failure Rate Calculations at 55°C and 60% CL			
	EDH (hours)	FITs	MTTF (hours)
Early Life	2.46E+08	3.7	2.68E+08
Constant (Random)	2.17E+09	0.4	2.36E+09

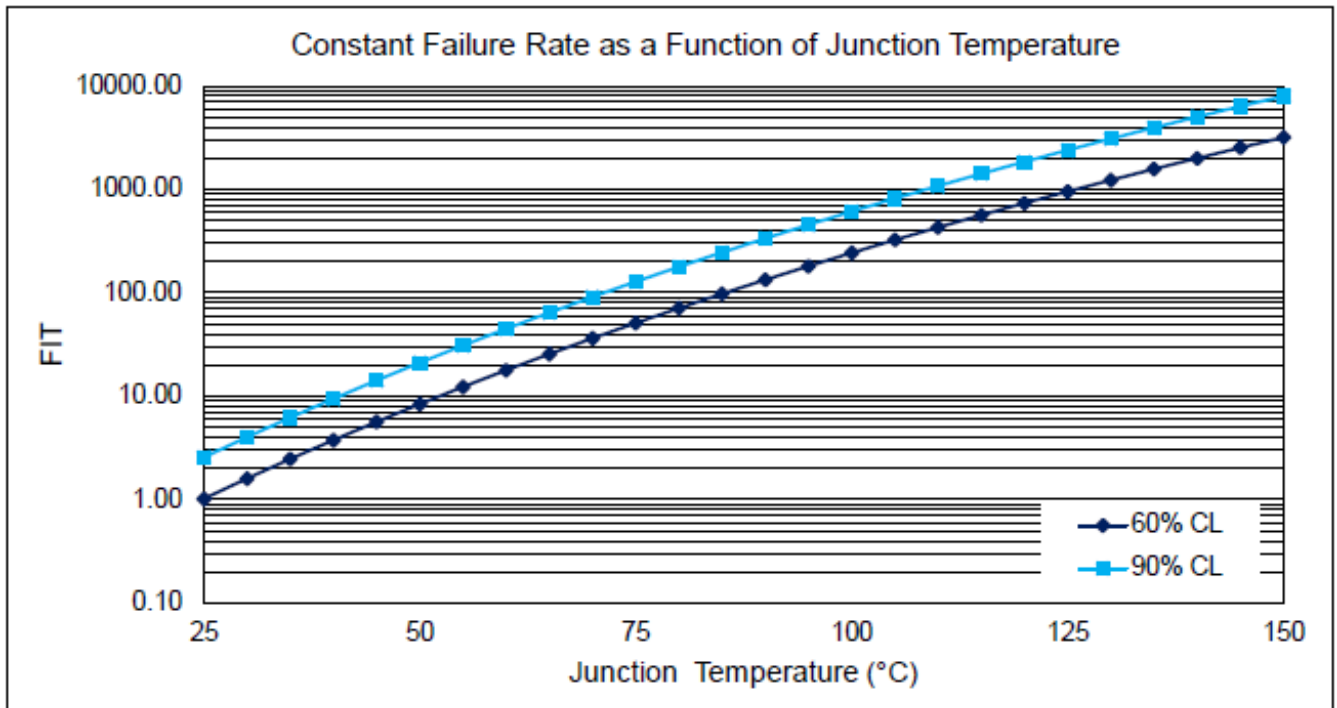




# Power Limiters (LMTR)

Description : UltraCMOS Power Limiters.  
 Products in Family : PE45450, PE45140, PE45361  
 Process Technology : UltraCMOS® 5, UltraCMOS® 8  
 Units Tested : 589

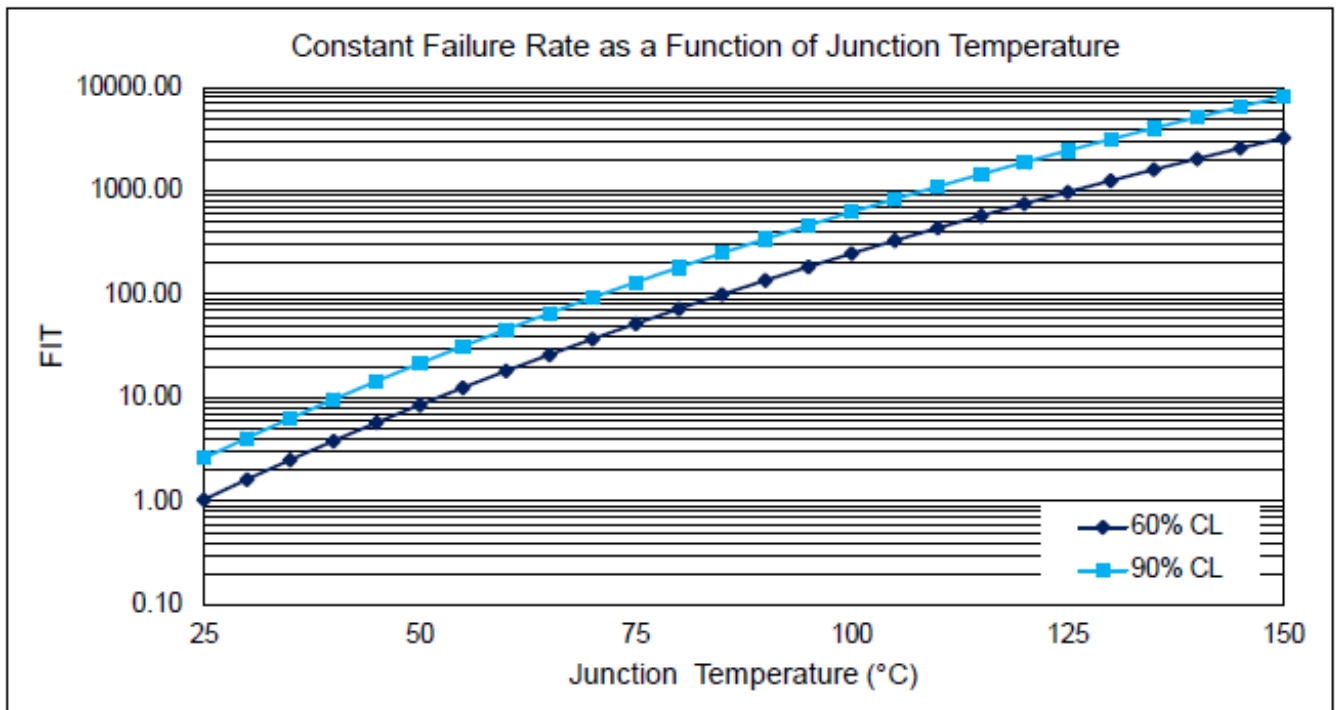
Standard Failure Rate Calculations at 55°C and 60% CL			
	EDH (hours)	FITs	MTTF (hours)
Early Life	7.04E+06	130.2	7.68E+06
Constant (Random)	7.45E+07	12.3	8.13E+07



# Monolithic Phase & Amplitude Controller (MPAC)

Description : UltraCMOS RF MPACs.  
 Products in Family : PE46120, PE46130, PE46140, PE19601  
 Process Technology : UltraCMOS<sup>®</sup> 5, UltraCMOS<sup>®</sup> 8  
 Units Tested : 565

Standard Failure Rate Calculations at 55°C and 60% CL			
	EDH (hours)	FITs	MTTF (hours)
Early Life	7.02E+06	130.6	7.66E+06
Constant (Random)	7.31E+07	12.5	7.98E+07



# Mixers (MXR)

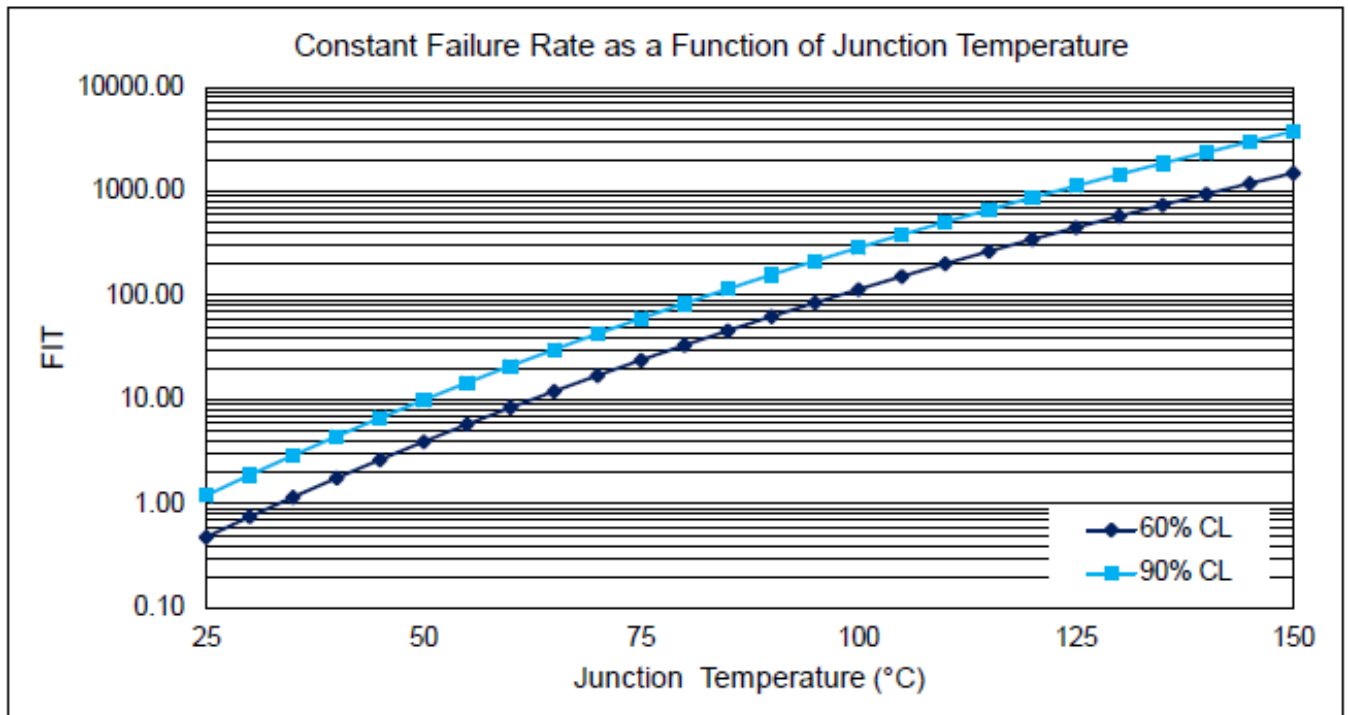
Description : UltraCMOS MOSFET quad array broadband and tuned mixers.

Products in Family : PE412x, PE413x, PE414x, PE4150, PE4151, PE4152, PE41901

Process Technology : UltraCMOS<sup>®</sup> 2, UltraCMOS<sup>®</sup> 8

Units Tested : 1, 158

Standard Failure Rate Calculations at 55°C and 60% CL			
	EDH (hours)	FITs	MTTF (hours)
Early Life	9.23E+06	99.2	1.01E+07
Constant (Random)	1.58E+08	5.8	1.73E+08



# PA Controller (PAC)

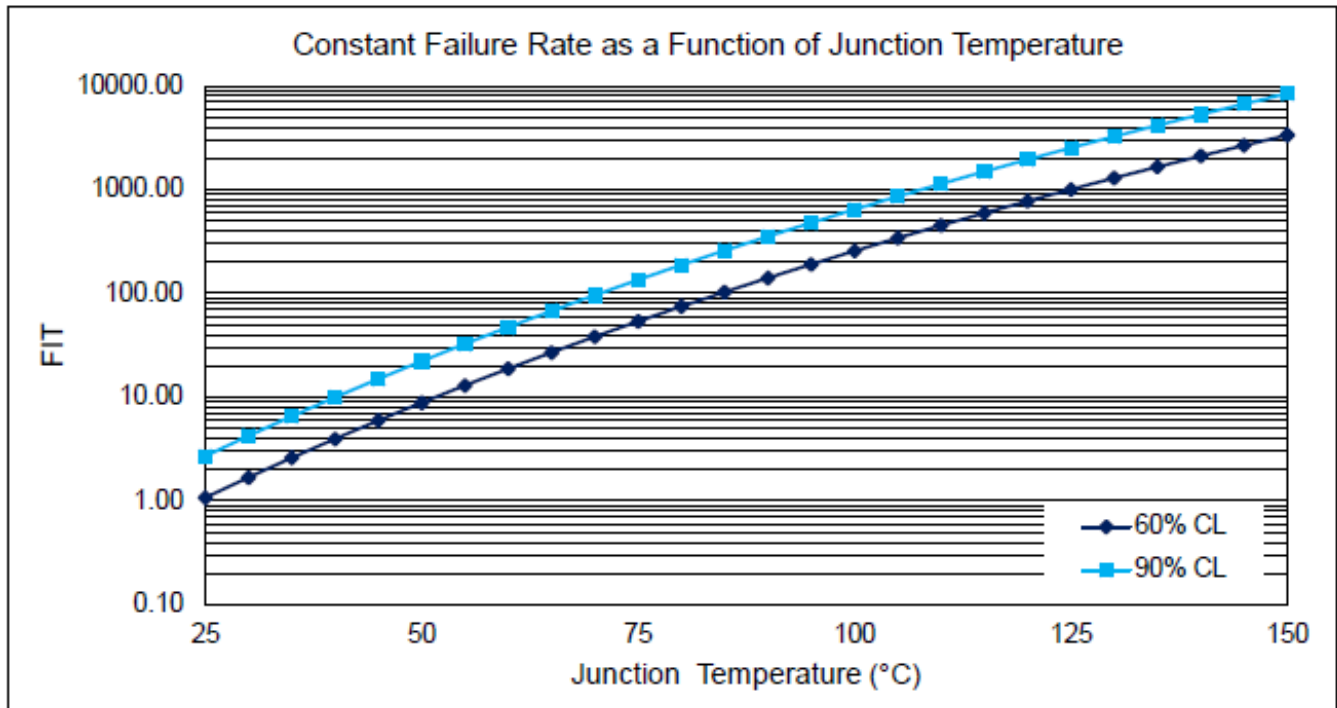
Description : PA Controller controls the PA bias current in PAD modules for RF Front Ends

Products in Family : PE515131

Process Technology : UltraCMOS® 12

Units Tested : 3,661

Standard Failure Rate Calculations at 55°C and 60% CL			
	EDH (hours)	FITs	MTTF (hours)
Early Life	1.50E+07	61.0	1.64E+07
Constant (Random)	7.07E+07	13.0	7.72E+07



# Phase Locked-Loop Synthesizers (PLL)

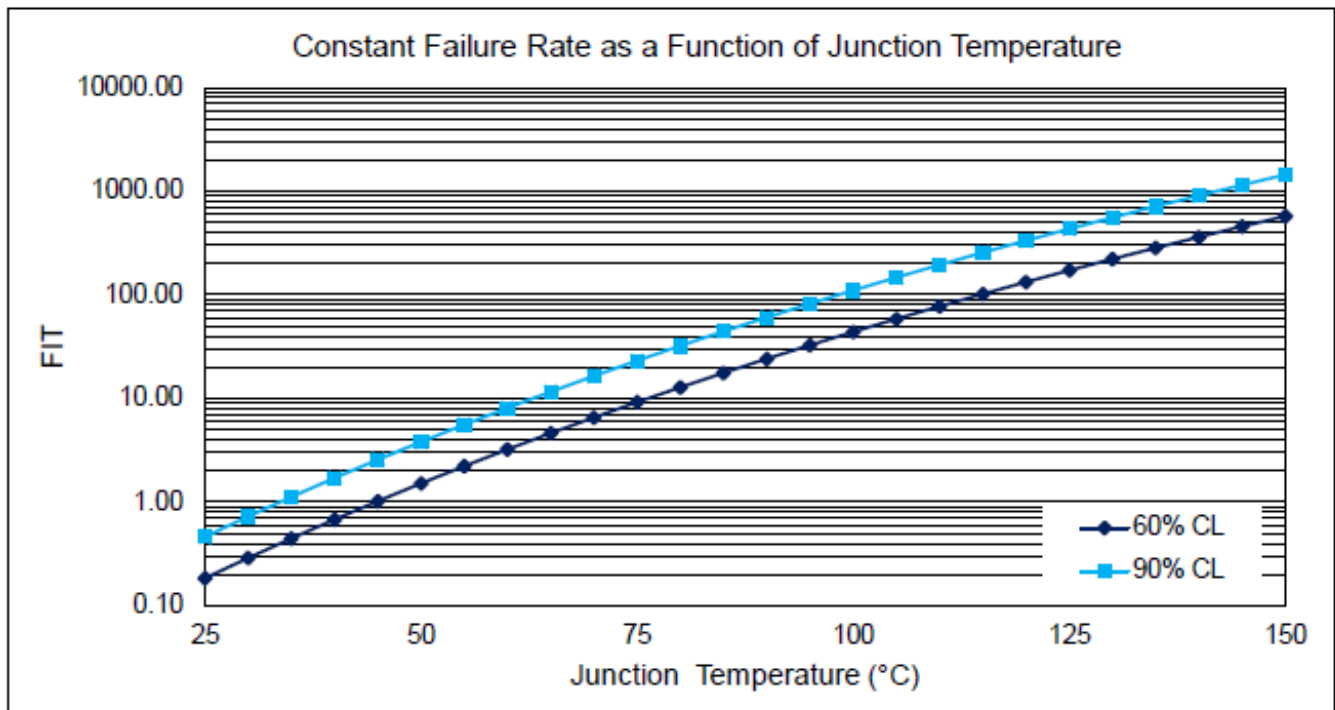
Description : Integer-N, Fractional-N and Delta Sigma Modulated frequency synthesizers for base station, mobile wireless and high reliability space applications.

Products in Family : PE323x, PE3240, PE329x, PE333x, PE334x, PE8334x, PE960x, PE970x, PE9702x, PE972x, PE97240, PE9763, PE97632, PE3324x, PE97640

Process Technology : UltraCMOS® 2, UltraCMOS® 5

Units Tested : 5,846

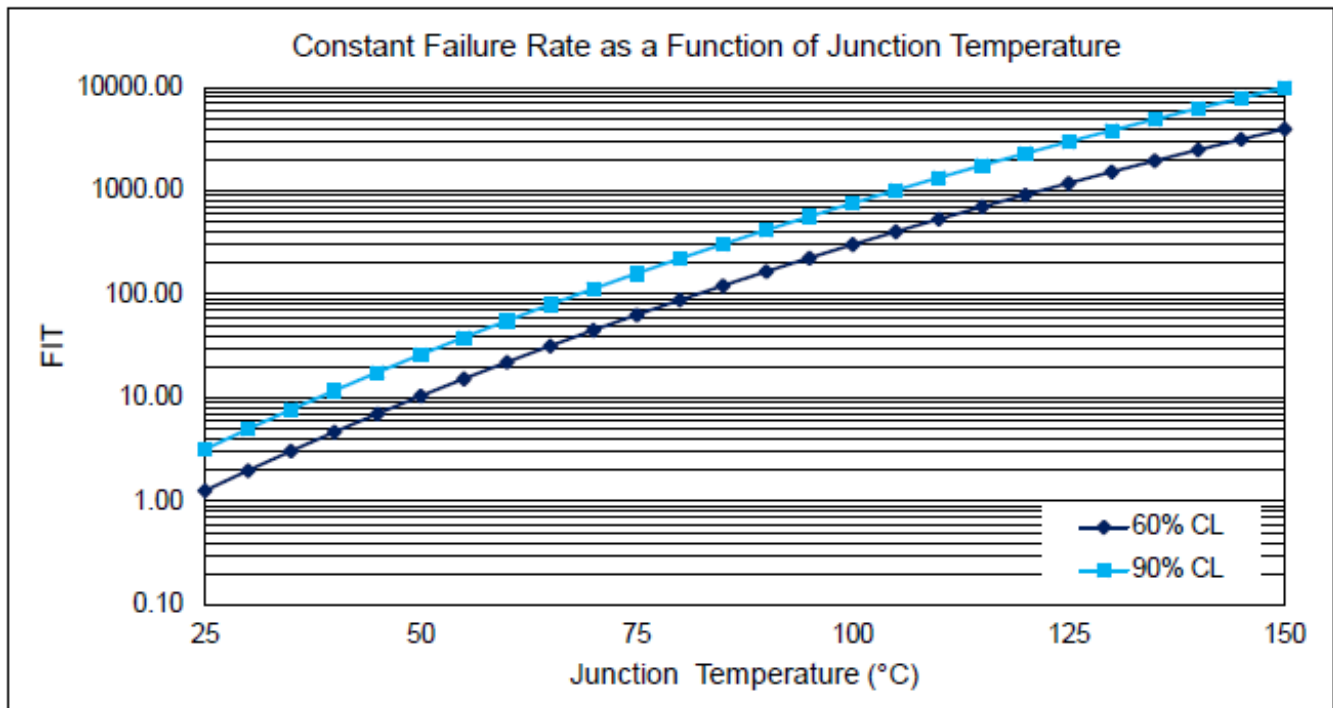
Standard Failure Rate Calculations at 55°C and 60% CL			
	EDH (hours)	FITs	MTTF (hours)
Early Life	2.95E+07	31.0	3.22E+07
Constant (Random)	4.13E+08	2.2	4.51E+08



# Phase Shifters (PSH)

Description : UltraCMOS RF Phase Shifters.  
 Products in Family : PE44820  
 Process Technology : UltraCMOS® 5  
 Units Tested : 432

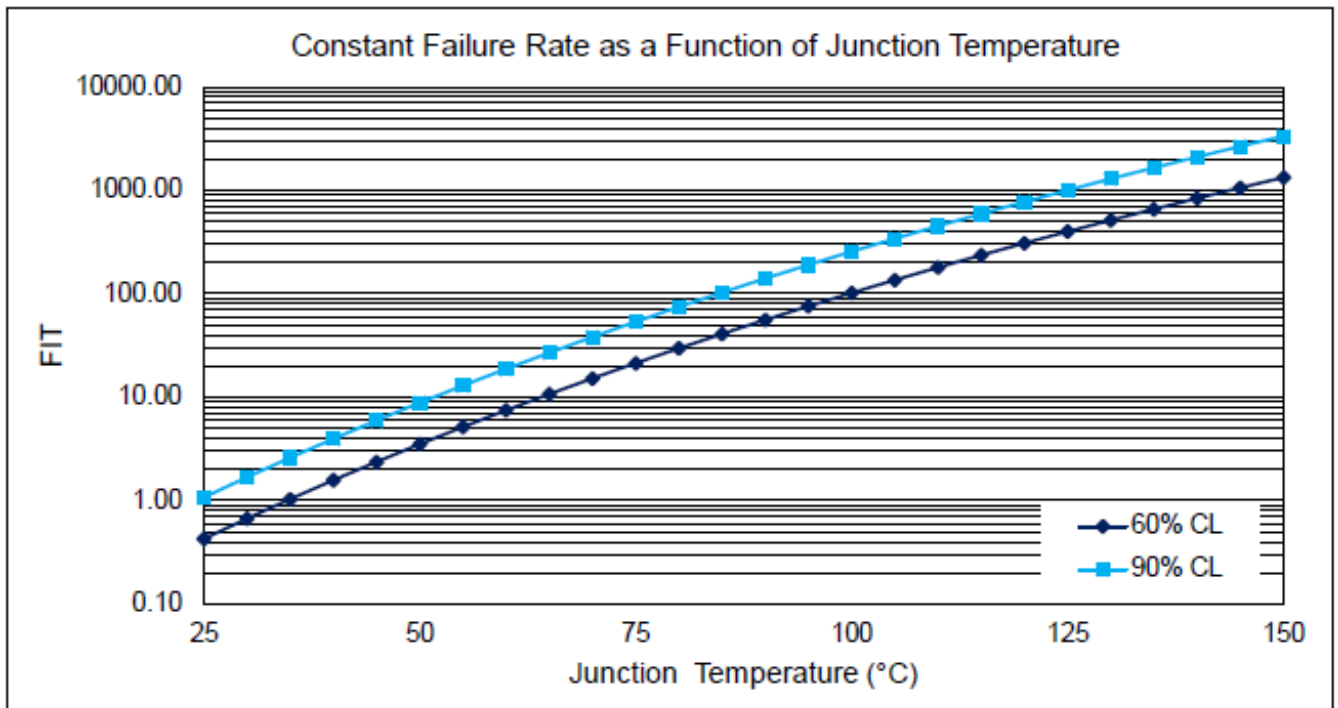
Standard Failure Rate Calculations at 55°C and 60% CL			
	EDH (hours)	FITs	MTTF (hours)
Early Life	5.37E+06	170.8	5.86E+06
Constant (Random)	6.00E+07	15.3	6.55E+07



# Prescalers (PSR)

Description : UltraCMOS RF Prescalers.  
 Products in Family : PE350x, PE351x, PE8350x, PE8351x, PE930x, PE931x, PE34500  
 Process Technology : UltraCMOS® 2, UltraCMOS® 3.5, UltraCMOS® 8  
 Units Tested : 2,432

Standard Failure Rate Calculations at 55°C and 60% CL			
	EDH (hours)	FITs	MTTF (hours)
Early Life	1.25E+07	73.5	1.36E+07
Constant (Random)	1.78E+08	5.1	1.94E+08



# Reliability Data

(Periodic Testing for the last 8 Quarters)



# High Temperature Operating Life (HTOL)

- Reference Standards : JESD22-A108
- Test Conditions :  $T_A = 125^\circ\text{C}$  (A) or  $150^\circ\text{C}$  (B)
- :  $V_{\text{bias}} = \text{max operating voltage}$
- Test Duration (typical) : 1,000 hrs. at (A) or 500 hrs. at (B) — HTOL  
48 hrs. at (A) or 24 hrs. at (B) — ELFR

HTOL & ELFR	2017	2017	2017	2017	2018	2018	2018	2018
Process Technology	Q1	Q2	Q3	Q4	Q1	Q2	Q3	Q4
UltraCMOS® 2	0/245	0/85	0/170	0/170	0/85	0/85	0/85	0/85
UltraCMOS® 3.5	0/85	0/85	0/77	0/77	-	0/77	0/77	0/77
UltraCMOS® 5	0/240	0/80	0/85	0/239	-	0/77	0/109	0/85
UltraCMOS® 6	-	-	-	-	-	-	-	-
UltraCMOS® 6.5	0/158	-	-	0/80	-	0/80	-	-
UltraCMOS® 8	-	0/112	0/32	-	-	-	-	-
UltraCMOS® 10	-	-	-	-	-	-	-	-
UltraCMOS® 11	0/357	0/77	0/701	0/77	0/3,866	0/176	0/950	0/539
UltraCMOS® 12	0/525	-	0/297	0/494	0/3,586	-	0/501	0/157
BCD Gen II	-	-	-	-	-	-	0/253	-

HTOL & ELFR	2017	2017	2017	2017	2018	2018	2018	2018
Product Family	Q1	Q2	Q3	Q4	Q1	Q2	Q3	Q4
Amplifier	0/357	0/77	0/378	0/77	0/3,866	0/176	0/1,120	0/539
ASW	0/605	-	0/382	0/579	0/85	-	0/360	0/77
Boost Converter	-	-	-	-	-	-	0/253	-
DCDC	-	-	0/238	-	-	-	-	-
DSA	0/158	-	0/85	-	-	-	-	-
DTC	-	-	-	-	-	-	-	-
GaN Driver	-	-	-	0/80	-	0/80	-	-
HPSW	0/410	0/362	0/247	0/316	-	0/239	0/162	0/247
LMTR	-	-	0/32	-	-	-	-	-
MPAC	-	-	-	-	-	-	-	-
MXR	-	-	-	0/85	0/85	-	-	-
PAC	-	-	-	-	0/3,501	-	0/80	0/80
PLL	-	-	-	-	-	-	-	-
PSH	0/80	-	-	-	-	-	-	-
PSR	-	-	-	-	-	-	-	-

# Temperature Cycle (TC)

Reference Standards : JESD22-A104  
 Test Conditions : -55°C to +125°C (B)  
 : -65°C to +150°C (C)  
 Test Duration (typical) : 1,000 cyc. at (B) or 500 cyc. at (C)

TC	2017	2017	2017	2017	2018	2018	2018	2018
Package Family	Q1	Q2	Q3	Q4	Q1	Q2	Q3	Q4
10L 2x2 FCETSLP	0/55	-	-	-	-	-	-	-
12L 2x2 QFN	0/55	0/55	0/45	0/45	-	0/45	0/45	0/45
12L 3x3 QFN	0/55	-	-	-	-	-	-	-
16L 3x3 QFN	0/110	0/165	-	-	-	-	-	-
20L 4x4 QFN	-	-	-	-	-	-	-	-
24L 4x4 FCLGA	0/55	0/55	0/55	0/45	-	0/45	0/300	0/50
24L 4x4 QFN	-	-	-	-	-	-	-	-
30L 3x3.8 QFN	0/55	-	-	-	-	-	-	-
32L 5x5 FCLGA	0/55	-	-	-	-	-	0/1,035	-
32L 5x5 QFN	0/205	-	-	-	-	-	-	-
44L PLCC	-	-	-	-	-	-	-	-
6L SC70	0/55	0/55	0/55	0/55	-	0/55	0/55	0/45
7L SOIC	-	-	-	-	-	-	-	-
8L MSOP	-	-	-	-	-	-	-	-
8L TSSOP	-	-	-	-	-	-	-	-

Note

- n/a - Reliability data not available. Package (family) not yet qualified at the specified period.
- dash (-) - Test not performed at the specified period.
- \* Plastic encapsulated packages had undergone MSL Preconditioning prior to test.

# Highly Accelerated Stress Test (HAST)

Reference Standards : JESD22-A110  
 Test Conditions : 130°C, 85% RH, 2.27 atm. (A)  
 : 110°C, 85% RH, 1.20 atm. (B)  
 Test Duration (typical) : 96 hrs. at (A) or 264 hrs. at (B)

HAST	2017	2017	2017	2017	2018	2018	2018	2018
Package Family	Q1	Q2	Q3	Q4	Q1	Q2	Q3	Q4
10L 2x2 FCETSLP	-	-	-	-	-	-	-	-
12L 2x2 QFN	0/55	0/55	-	0/45	-	0/45	0/45	0/45
12L 3x3 QFN	-	-	-	-	-	-	-	-
16L 3x3 QFN	0/55	0/239	-	-	-	-	-	-
20L 4x4 QFN	-	-	-	-	-	-	-	-
24L 4x4 FCLGA	-	-	0/55	-	-	-	-	-
24L 4x4 QFN	-	-	-	-	-	-	-	-
30L 3x3.8 QFN	-	-	-	-	-	-	-	-
32L 5x5 FCLGA	-	-	-	-	-	-	0/135	-
32L 5x5 QFN	-	-	-	-	-	-	-	-
44L PLCC	-	-	-	-	-	-	-	-
6L SC70	0/55	0/50	0/55	0/55	-	0/55	0/55	0/45
7L SOIC	-	-	-	-	-	-	-	-
8L MSOP	-	-	-	-	-	-	-	-
8L TSSOP	-	-	-	-	-	-	-	-

Note

- n/a - Reliability data not available. Package (family) not yet qualified at the specified period.
- dash (-) - Test not performed at the specified period. HAST may not apply to hermetic packages.
- \* Plastic encapsulated packages had undergone MSL Preconditioning prior to test.

# High Temperature Storage (HTS)

Reference Standards : JESD22-A103

Test Conditions : Ta = 150°C

Test Duration (typical) : 1,000 hrs.

HTS	2017	2017	2017	2017	2018	2018	2018	2018
Package Family	Q1	Q2	Q3	Q4	Q1	Q2	Q3	Q4
10L 2x2 FCETSLP	0/83	-	-	-	-	-	-	-
12L 2x2 QFN	0/85	0/85	0/77	0/77	-	0/77	-	0/154
12L 3x3 QFN	0/80	-	-	-	-	-	-	-
16L 3x3 QFN	0/160	0/255	-	-	-	-	-	-
20L 4x4 QFN	-	-	-	-	-	-	-	-
24L 4x4 FCLGA	0/80	0/80	0/85	0/77	-	0/77	-	0/85
24L 4x4 QFN	0/80	-	-	-	-	-	-	-
30L 3x3.8 QFN	0/80	-	-	-	-	-	-	-
32L 5x5 FCLGA	0/80	-	-	-	-	-	0/135	-
32L 5x5 QFN	0/80	-	-	-	-	-	-	-
44L PLCC	-	-	-	-	-	-	-	-
6L SC70	0/85	0/85	0/85	0/85	-	0/85	-	0/170
7L SOIC	-	-	-	-	-	-	-	-
8L MSOP	-	-	-	-	-	-	-	-
8L TSSOP	-	-	-	-	-	-	-	-

Note

n/a - Reliability data not available. Package (family) not yet qualified at the specified period.

dash (-) - Test not performed at the specified period.